

iC-LF1401

128x1 Linear Image Sensor



Rev A3, Page 1/9

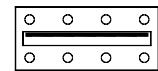
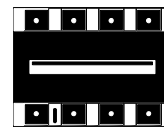
FEATURES

- ◆ 128 active photo pixels of 56 μm at a 63.5 μm pitch (400 DPI)
- ◆ Integrating L-V conversion followed by a sample & hold circuit
- ◆ High sensitivity and uniformity over wavelength
- ◆ High clockrates of up to 5 MHz
- ◆ Only 128 clocks required for readout
- ◆ Shutter function enables flexible integration times
- ◆ Glitch-free analogue output
- ◆ Push-pull output amplifier
- ◆ 5 V single supply operation
- ◆ Can run off external bias to reduce power consumption
- ◆ Pin-to-pin compatible with TSL1401

APPLICATIONS

- ◆ Optical line image sensors
- ◆ CCD substitute

PACKAGES



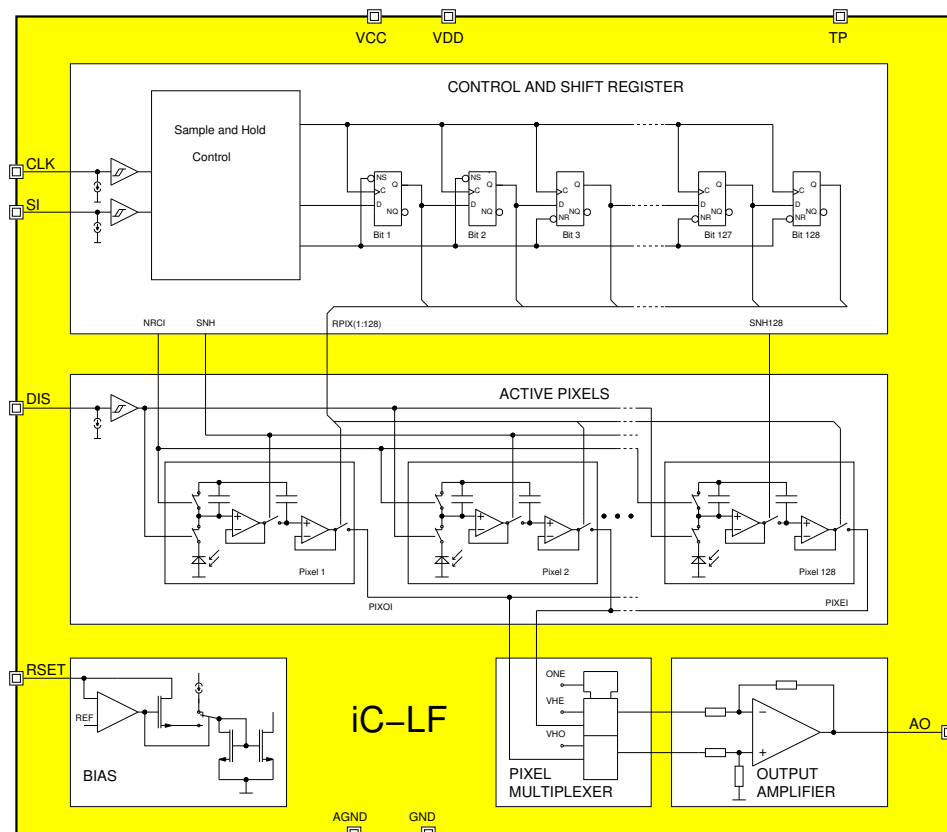
OLGA LF2C

OBGA™ LF3C



Die size (8.5 mm x 1.6 mm)

BLOCK DIAGRAM



iC-LF1401

128x1 Linear Image Sensor



Rev A3, Page 2/9

DESCRIPTION

iC-LF1401 is an integrating light-to-voltage converter with a line of 128 pixels pitched at $63.5\ \mu\text{m}$ (center-to-center distance). Each pixel consists of a $56.4\ \mu\text{m} \times 200\ \mu\text{m}$ photodiode and an integration capacitor with a sample-and-hold circuit.

The integrated control logic makes operation very simple, with only a start and clock signal necessary. A third control input (DIS) enables the integration to be suspended at any time (electronic shutter).

When the start signal is given hold mode is acti-

vated for all pixels simultaneously with the next leading clock edge; starting with pixel 1 the hold voltages are switched in sequence to the push-pull output amplifier. The second clock pulse resets all integration capacitors and the integration period starts again in the background during the output phase. A run is complete after 128 clock pulses.

iC-LF1401 is suitable for high clock rates of up to 5 MHz. If this is not required the supply current can be reduced via the external bias setting (current into pin RSET).

iC-LF1401

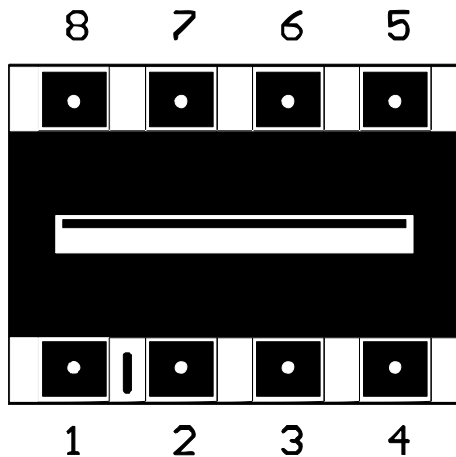
128x1 Linear Image Sensor



Rev A3, Page 3/9

PACKAGES OLGA LF2C, OBGA™ LF3C

PIN CONFIGURATION OLGA LF2C (top view)

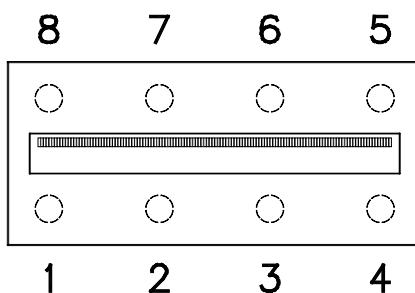


PIN FUNCTIONS

No. Name Function

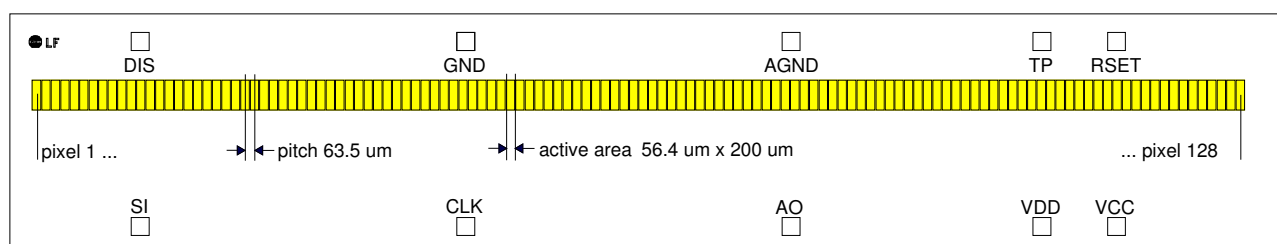
- | | | |
|---|------|--|
| 1 | SI | Start Integration Input |
| 2 | CLK | Clock Input |
| 3 | AO | Analogue Output |
| 4 | VCC | +5 V Supply Voltage |
| 5 | RSET | Bias Current (connected to GND for internal bias = default; resistor from VCC to RSET for reduced current consumption) |
| 6 | AGND | Analogue Ground |
| 7 | GND | Digital Ground |
| 8 | DIS | Hold Integration Input |

PIN CONFIGURATION OBGA™ LF3C (top view)



CHIP LAYOUT

Die size: 8.5 mm x 1.6 mm



iC-LF1401

128x1 Linear Image Sensor



Rev A3, Page 4/9

ABSOLUTE MAXIMUM RATINGS

Beyond these values damage may occur; device operation is not guaranteed.

Item No.	Symbol	Parameter	Conditions	Fig.	Limits		Unit
					Min.	Max.	
G001	VDD	Digital Supply Voltage			-0.3	6	V
G002	VCC	Analog Supply Voltage			-0.3	6	V
G003	V()	Voltage at SI, CLK, DIS, RSET, TP, AO			-0.3	VCC + 0.3	V
G004	I()	Current in RSET, TP, AO			-10	10	mA
G005	Vd()	ESD Susceptibility at all pins	MIL-STD-883, Method 3015, HBM 100 pF discharged through 1.5 kΩ			2	kV
G006	Tj	Operating Junction Temperature			-40	125	°C
G007	Ts	Storage Temperature Range	see package specification				

THERMAL DATA

Operating Conditions: VCC = VDD = 5 V ±10%

Item No.	Symbol	Parameter	Conditions	Fig.	Limits			Unit
					Min.	Typ.	Max.	
T01	Ta	Operating Ambient Temperature Range (extended range on request)	see package specification					

All voltages are referenced to ground unless otherwise stated.

All currents into the device pins are positive; all currents out of the device pins are negative.

www.ic-haus.com

iC-LF1401

128x1 Linear Image Sensor



Rev A3, Page 5/9

ELECTRICAL CHARACTERISTICS

Operating Conditions: VCC = VDD = 5 V ±10%, RSET = GND, Tj = -25...85 °C unless otherwise noted

Item No.	Symbol	Parameter	Conditions	Tj °C	Fig.				Unit
						Min.	Typ.	Max.	
Total Device									
001	VDD	Digital Supply Voltage Range				4.5		5.5	V
002	VCC	Analog Supply Voltage Range				4.5		5.5	V
003	I(VDD)	Supply Current in VDD	f(CLK) = 1 MHz				200	300	µA
004	I(VCC)	Supply Current in VCC					8	13	mA
005	Vc()hi	Clamp Voltage hi at SI, CLK,DIS, TP, RSET	Vc()hi = V() – V(VCC), I() = 1 mA			0.3		1.8	V
006	Vc()lo	Clamp Voltage lo at SI, CLK,DIS, TP, RSET	Vc()hi = V() – V(AGND), I() = -1 mA			-1.5		-0.3	V
007	Vc()hi	Clamp Voltage hi at AO	Vc()hi = V(AO) – V(VCC), I(AO) = 1 mA			0.3		1.5	V
008	Vc()lo	Clamp Voltage lo at AO, VCC, VDD, GND	Vc()lo = V() – V(AGND), I() = -1 mA			-1.5		-0.3	V
Photodiode Array									
201	A()	Radiant Sensitive Area	200 µm x 56.40 µm per Pixel				0.01128		mm ²
202	S(λ)max	Spectral Sensitivity	λ = 680 nm				0.5		A/W
203	λ ar	Spectral Application Range	S(λ ar) = 0.25 x S(λ)max			400		980	nm
Analogue Output AO									
301	Vs()lo	Saturation Voltage lo	I() = 1 mA					0.5	V
302	Vs()hi	Saturation Voltage hi	Vs()hi = VCC – V(), I() = -1 mA					1	V
303	K	Sensitivity	λ = 680 nm, package OLGA LF2C				2.88		V/pWs
304	V0()	Offset Voltage	integration time 1 ms, no illumination				400	800	mV
305	ΔV0()	Offset Voltage Deviation during integration mode	ΔV0() = V(AO)t1 – V(AO)t2, Δt = t2 – t1 = 1 ms			-250		50	mV
306	ΔV()	Signal Deviation during hold mode	ΔV0() = V(AO)t1 – V(AO)t2, Δt = t2 – t1 = 1 ms			-150		150	mV
307	tp(CLK-AO)	Settling Time	Cl(AO) = 10 pF, CLK lo → hi until V(AO) = 0.98 x V(VCC)					200	ns
Power-On Reset									
801	VCCon	Power-On Release by VCC						4.4	V
802	VCCoff	Power-Down Reset by VCC				1			V
803	VCChys	Hysteresis	VCChys = VCCon – VCCoff			0.4	1	2	V
Bias Current Adjust RSET									
901	Ibias()	Permissible External Bias Current				20		100	µA
902	Vref	Reference Voltage	I(RSET) = Ibias			2.5	3	3.5	V
Input Interface SI, CLK, DIS									
B01	Vt()hi	Threshold Voltage hi			2	1.4		1.8	V
B02	Vt()lo	Threshold Voltage lo			2	0.9		1.2	V
B03	Vt()hys	Hysteresis	Vt()hys = Vt()hi – Vt()lo		2	300		800	mV
B04	I()	Pull-Down Current				10	30	50	µA
B05	fclk	Permissible Clock Frequency						5	MHz

iC-LF1401

128x1 Linear Image Sensor



Rev A3, Page 6/9

OPTICAL CHARACTERISTICS: Diagrams

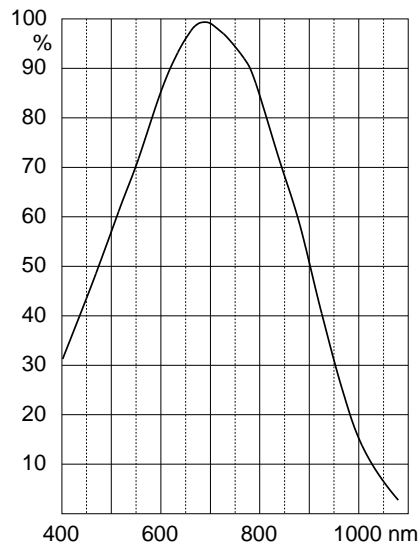


Figure 1: Relative spectral sensitivity

OPERATING REQUIREMENTS: Logic

Operating Conditions: $V_{CC} = V_{DD} = 5\text{ V} \pm 10\%$, $T_j = -25 \dots 85\text{ }^\circ\text{C}$
input levels lo = 0...0.45 V, hi = 2.4 V...VCC, see Fig. 2 for reference levels

Item No.	Symbol	Parameter	Conditions	Fig.	Min. / Max.		Unit
					Min.	Max.	
I001	tset	Setup Time: SI stable before CLK lo \rightarrow hi		3	50		ns
I002	thold	Hold Time: SI stable after CLK lo \rightarrow hi		3	50		ns

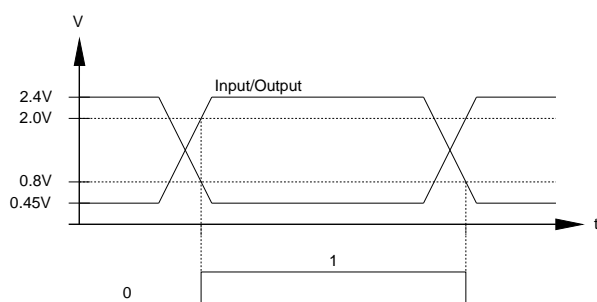


Figure 2: Reference levels

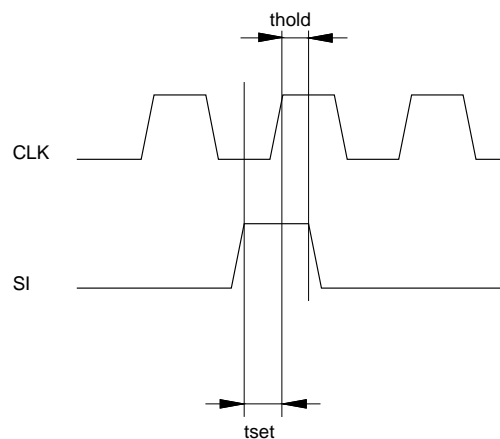


Figure 3: Timing diagram

DESCRIPTION OF FUNCTIONS

Normal operation

Following an internal power-on reset the integration and hold capacitors are discharged and the sample and hold circuit is set to sample mode. A high signal at SI and a rising edge at CLK triggers a readout cycle and with it a new integration cycle.

In this process the hold capacitors of pixels 1 to 127 are switched to hold mode immediately ($SNH = 1$),

with pixel 128 ($SNH_{128} = 1$) following suit one clock pulse later. This special procedure allows all pixels to be read out with just 128 clock pulses. The integration capacitors are discharged by a one clock long reset signal ($NRCI = 0$) which occurs between the 2nd and 3rd falling edge of the readout clock pulse (cf. Figure 4). After the 127 pixels have been read out these are again set to sample mode ($SNH = 0$), likewise for pixel 128 one clock pulse later ($SNH_{128} = 0$).

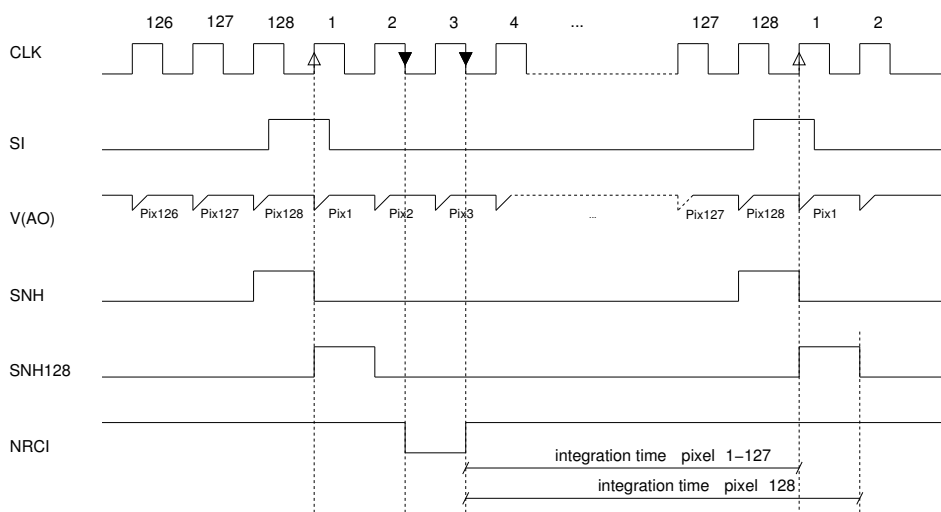


Figure 4: Readout cycle and integration sequence

If prior to the 128th clock pulse a high signal occurs at SI the present readout is halted and immediately reinitiated with pixel 1. In this instance the hold ca-

pacitors retain their old value i.e. hold mode prevails ($SNH/SNH_{128} = 0$).

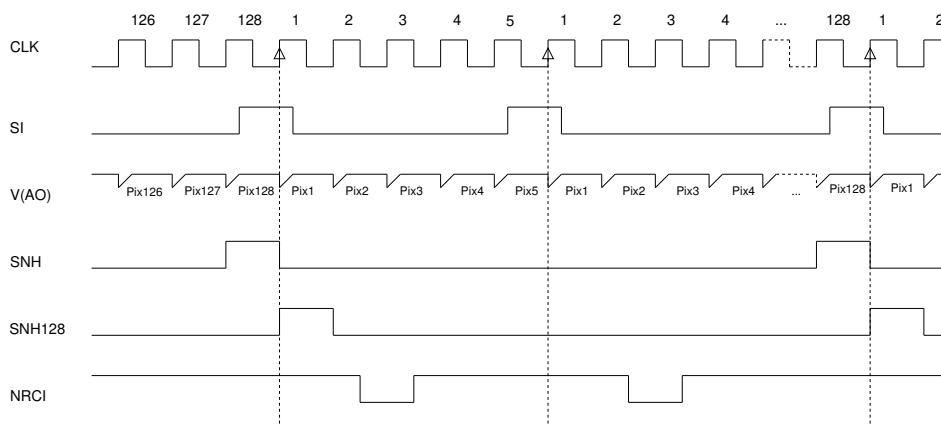


Figure 5: Restarting a readout cycle

With more than 128 clock pulses until the next SI signal, pixel 1 is output without entering hold mode; the

output voltage tracks the voltage of the pixel 1 integration capacitor.

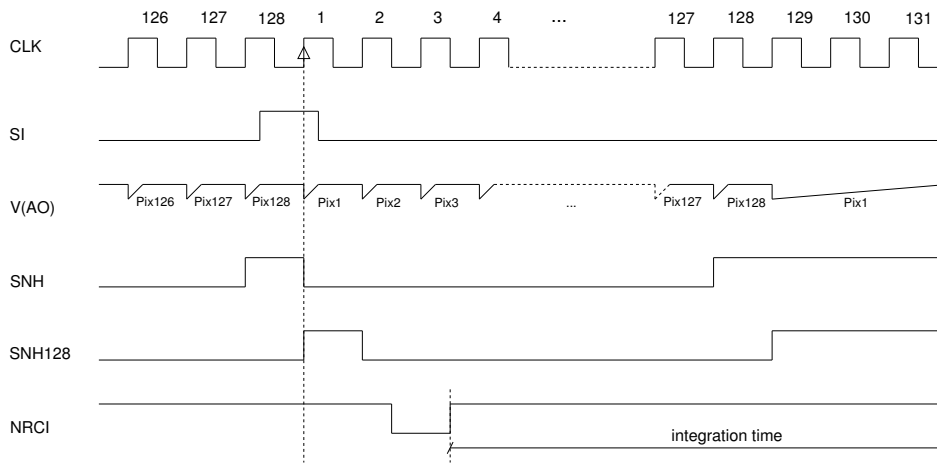


Figure 6: Clock pulse continued without giving a new integration start signal

Operation with the shutter function

Integration can be suspended at any time via pin DIS, i.e. the photodiodes are disconnected from their corresponding integration capacitor when DIS is high and

the current integration capacitor voltages are maintained. If this pin is open or switched to GND the pixel photocurrents are summed up by the integration capacitors until the next successive SI signal follows.

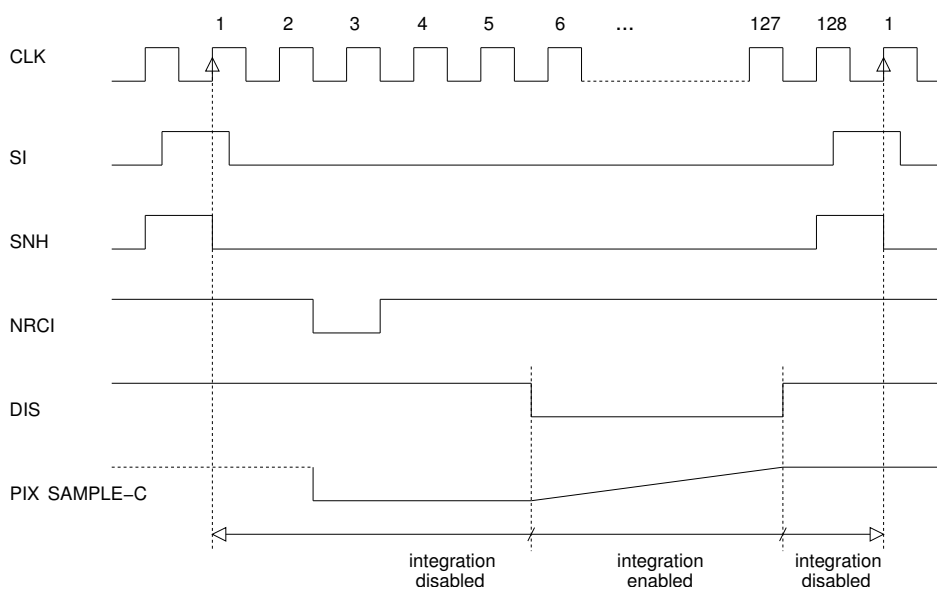


Figure 7: Defining the integration time via shutter input DIS

External bias current setting

In order to reduce the power consumption of the device an external reference current can be supplied to pin RSET which reduces the maximum readout frequency,

however. To this end a resistor must be connected from VCC to RSET. If this pin is not used, it should be connected to GND.

This specification is for a newly developed product. iC-Haus therefore reserves the right to change or update, without notice, any information contained herein, design and specification; and to discontinue or limit production or distribution of any product versions. Please contact iC-Haus to ascertain the current data. Copying – even as an excerpt – is only permitted with iC-Haus approval in writing and precise reference to source. iC-Haus does not warrant the accuracy, completeness or timeliness of the specification on this site and does not assume liability for any errors or omissions in the materials. The data specified is intended solely for the purpose of product description. No representations or warranties, either express or implied, of merchantability, fitness for a particular purpose or of any other nature are made hereunder with respect to information/specification or the products to which information refers and no guarantee with respect to compliance to the intended use is given. In particular, this also applies to the stated possible applications or areas of applications of the product. iC-Haus conveys no patent, copyright, mask work right or other trade mark right to this product. iC-Haus assumes no liability for any patent and/or other trade mark rights of a third party resulting from processing or handling of the product and/or any other use of the product.

iC-LF1401

128x1 Linear Image Sensor



Rev A3, Page 9/9

ORDERING INFORMATION

Type	Package	Order Designation
iC-LF	OLGA LF2C OBGA™ LF3C -	iC-LF OLGA LF2C iC-LF OBGA LF3C iC-LF chip

For information about prices, terms of delivery, other packaging options etc. please contact:

iC-Haus GmbH
Am Kuemmerling 18
D-55294 Bodenheim
GERMANY

Tel.: +49 (61 35) 92 92-0
Fax: +49 (61 35) 92 92-192
Web: <http://www.ichaus.com>
E-Mail: sales@ichaus.com